Top View


## Plugs onto SF-BGA352E-B-42(F) IE part \#

## Features

Direclty mates with a comapatoble SMT adapter.
Minimum real estate required
Compression plate distributes evenly
Clamshell lid

## Materials:

Clam Shell Lid: Black anodized Aluminum.
1 Height $=20 \mathrm{~mm}$.
Socket Base: Black anodized Aluminum.
Height $=6 \mathrm{~mm}$.
3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm .

4 Compression Screw: Clear anodized Aluminum. Height $=27 \mathrm{~mm}$, Fluted Knob

## Stamped Pin:

Stamped Contact: BeCu , Au Plate
Spring SS, Au Plate
6 Pogo Pin Guides: Peek
Pogo Pin Guide Screw: Pan head phillips, 18-8
17 SS ,
0-80 thread, $3 / 16^{\prime \prime}$ long.
8 Latch: Black anodized Aluminum.
Substrate: $3.18 \mathrm{~mm} \pm 0.125 \mathrm{~mm}\left[0.125{ }^{\prime \prime} \pm 0.005^{\prime \prime}\right]$
9 FR4/G10 or equivalent high temp material. Non-clad.
Pin: Brass - PS-2
10 Plating: 10u" Au over 50u" Ni min.

| CBT-BGA-6008 Drawing | Status: Released | Scale: 3:1 | Rev: A |
| :---: | :--- | :--- | :--- |
| © 2010 IRONWOOD ELECTRONICS, INC. <br> Tele: (952) 229-8200 | Drawing: V.Panavala | Date: 10/21/2010 |  |

Recommended PCB Layout Tolerances: $\pm 0.025 \mathrm{~mm}[ \pm 0.001 "]$ unless stated otherwise

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## Compatible BGA Spec




SIDE VIEW

1. Dimensions are in millimeters
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

Array $22 \times 22$
3 Dimension $b$ is measured at the maximum
solder ball diameter, parallel to datum plane $Z$.Datum $Z$ (seating plane) is defined by the spherical crowns of the solder balls.

5 Parallelism measurement shall exclude any effect of mark on top surface of package.

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